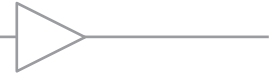


COMLINEAR[®] CLC1009, CLC1019, CLC2009

0.2mA, Low Cost, 2.5 to 5.5V, 35MHz

Rail-to-Rail Amplifiers



FEATURES

- 208 μ A supply current
- 35MHz bandwidth
- Power down to 35 μ A (CLC1019)
- Input voltage range with 5V supply: -0.3V to 3.8V
- Output voltage range with 5V supply: 0.08V to 4.88V
- 27V/ μ s slew rate
- 21nV/ $\sqrt{\text{Hz}}$ input voltage noise
- 13mA linear output current
- Fully specified at 2.7V and 5V supplies
- Replaces MAX4281
- CLC1009: Pb-free SOT23-5, SOIC-8
- CLC1019: Pb-free SOT23-6, SOIC-8
- CLC2009: Pb-free MSOP-8, SOIC-8

APPLICATIONS

- Portable/battery-powered applications
- Mobile communications, cell phones, pagers
- ADC buffer
- Active filters
- Portable test instruments
- Signal conditioning
- Medical Equipment
- Portable medical instrumentation

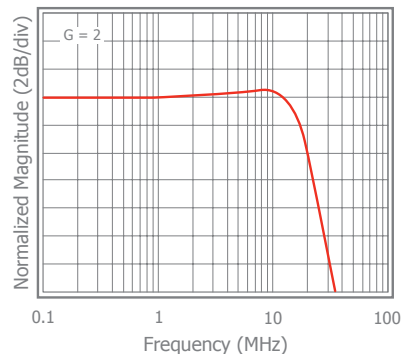
General Description

The COMLINEAR CLC1009 (single), CLC1019 (single with disable), and CLC2009 (dual) are ultra-low power, low cost, voltage feedback amplifiers. These amplifiers use only 208 μ A of supply current and are designed to operate from a supply range of 2.5V to 5.5V (± 1.25 to ± 2.75). The input voltage range extends 300mV below the negative rail and 1.2V below the positive rail.

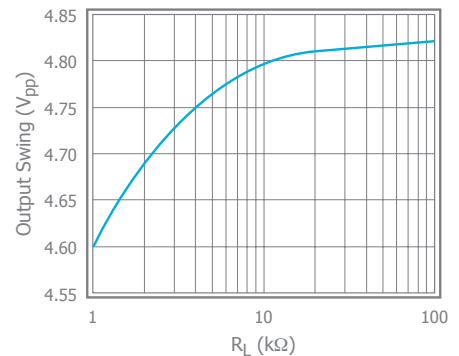
The CLC1009, CLC1019, and CLC2009 offer high bipolar performance at a low CMOS price. They offer superior dynamic performance with a 35MHz small signal bandwidth and 27V/ μ s slew rate. The combination of lowpower, high bandwidth, and rail-to-rail performance make the CLC1009, CLC1019, and CLC2009 well suited for battery-powered communication/ computing systems.

Typical Performance Examples

Frequency Response



Output Swing vs. R_L



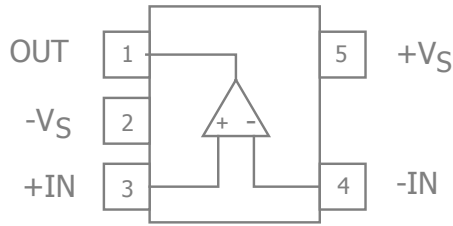
Ordering Information

Part Number	Package	Pb-Free	RoHS Compliant	Operating Temperature Range	Packaging Method
CLC1009IST5X*	SOT23-5	Yes	Yes	-40°C to +85°C	Reel
CLC1009ISO8X	SOIC-8	Yes	Yes	-40°C to +85°C	Reel
CLC1019IST6X*	SOT23-6	Yes	Yes	-40°C to +85°C	Reel
CLC1019ISO8X	SOIC-8	Yes	Yes	-40°C to +85°C	Reel
CLC2009IMP8X*	MSOP-8	Yes	Yes	-40°C to +85°C	Reel
CLC2009ISO8X	SOIC-8	Yes	Yes	-40°C to +85°C	Reel

Moisture sensitivity level for all parts is MSL-1. *Advance Information, contact CADEKA for availability.



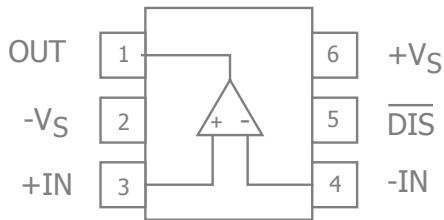
CLC1009 Pin Configuration



CLC1009 Pin Assignments

Pin No.	Pin Name	Description
1	OUT	Output
2	-VS	Negative supply
3	+IN	Positive input
4	-IN	Negative input
5	+VS	Positive supply

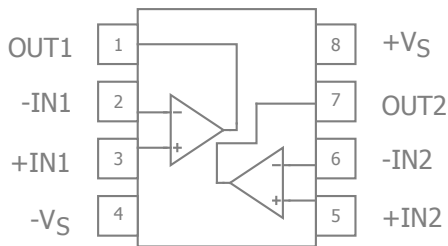
CLC1019 Pin Configuration



CLC1019 Pin Configuration

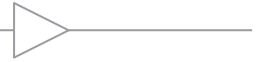
Pin No.	Pin Name	Description
1	OUT	Output
2	-VS	Negative supply
3	+IN	Positive input
4	-IN	Negative input
5	DIS	Disable pin. Enabled if pin is left floating or tied to +VS, disabled if pin is tied to -VS (which is GND in a single supply application).
6	+VS	Positive supply

CLC2009 Pin Configuration



CLC2009 Pin Configuration

Pin No.	Pin Name	Description
1	OUT1	Output, channel 1
2	-IN1	Negative input, channel 1
3	+IN1	Positive input, channel 1
4	-VS	Negative supply
5	+IN2	Positive input, channel 2
6	-IN2	Negative input, channel 2
7	OUT2	Output, channel 2
8	+VS	Positive supply



Absolute Maximum Ratings

The safety of the device is not guaranteed when it is operated above the "Absolute Maximum Ratings". The device should not be operated at these "absolute" limits. Adhere to the "Recommended Operating Conditions" for proper device function. The information contained in the Electrical Characteristics tables and Typical Performance plots reflect the operating conditions noted on the tables and plots.

Parameter	Min	Max	Unit
Supply Voltage	0	6	V
Input Voltage Range	$-V_S - 0.5V$	$+V_S + 0.5V$	V
Continuous Output Current	-30	30	mA

Reliability Information

Parameter	Min	Typ	Max	Unit
Junction Temperature			175	°C
Storage Temperature Range	-65		150	°C
Lead Temperature (Soldering, 10s)			260	°C
Package Thermal Resistance				
5-Lead SOT23		221		°C/W
6-Lead SOT23		177		°C/W
8-Lead SOIC		100		°C/W
8-Lead MSOP		139		°C/W

Notes:

Package thermal resistance (θ_{JA}), JEDEC standard, multi-layer test boards, still air.

ESD Protection

Product	SOT23-5	SOT23-6	SOIC-8	MSOP-8
Human Body Model (HBM)	TBD	TBD	TBD	TBD
Charged Device Model (CDM)	TBD	TBD	TBD	TBD

Recommended Operating Conditions

Parameter	Min	Typ	Max	Unit
Operating Temperature Range	-40		+85	°C
Supply Voltage Range	2.5		5.5	V



Electrical Characteristics at +2.7V

$T_A = 25^\circ\text{C}$, $V_S = +2.7\text{V}$, $R_f = R_g = 2.5\text{k}\Omega$, $R_L = 2\text{k}\Omega$ to $V_S/2$, $G = 2$; unless otherwise noted.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Frequency Domain Response						
$UGBW_{SS}$	Unity Gain -3dB Bandwidth	$G = +1$, $V_{OUT} = 0.05V_{pp}$, $R_f = 0$		28		MHz
BW_{SS}	-3dB Bandwidth	$G = +2$, $V_{OUT} < 0.2V_{pp}$		15		MHz
BW_{LS}	Large Signal Bandwidth	$G = +2$, $V_{OUT} = 2V_{pp}$		7		MHz
GBWP	Gain Bandwidth Product	$G = +11$, $V_{OUT} = 0.2V_{pp}$		16		MHz
Time Domain Response						
t_R , t_F	Rise and Fall Time	$V_{OUT} = 0.2\text{V}$ step; (10% to 90%)		16		ns
t_S	Settling Time to 0.1%	$V_{OUT} = 1\text{V}$ step		140		ns
OS	Overshoot	$V_{OUT} = 1\text{V}$ step		1		%
SR	Slew Rate	2V step, $G = -1$		20		V/ μs
Distortion/Noise Response						
HD2	2nd Harmonic Distortion	$V_{OUT} = 1V_{pp}$, 100kHz		-85		dBc
HD3	3rd Harmonic Distortion	$V_{OUT} = 1V_{pp}$, 100kHz		-63		dBc
THD	Total Harmonic Distortion	$V_{OUT} = 1V_{pp}$, 100kHz		62		dB
e_n	Input Voltage Noise	> 10kHz		23		nV/ $\sqrt{\text{Hz}}$
X_{TALK}	Crosstalk	$V_{OUT} = 0.2V_{pp}$, 100kHz		98		dB
DC Performance						
V_{IO}	Input Offset Voltage			0.8		mV
dV_{IO}	Average Drift			11		$\mu\text{V}/^\circ\text{C}$
I_b	Input Bias Current			0.37		μA
dI_b	Average Drift			1		nA/ $^\circ\text{C}$
I_{OS}	Input Offset Current			8		nA
PSRR	Power Supply Rejection Ratio ⁽¹⁾	DC	56	60		dB
A_{OL}	Open-Loop Gain	$V_{OUT} = V_S / 2$		65		dB
I_S	Supply Current	per channel		185		μA
Disable Characteristics						
T_{ON}	Turn On Time			1		μs
T_{OFF}	Turn Off Time			3.5		μs
OFF_{ISO}	Off Isolation	1MHz		74		dB
I_{SD}	Disable Supply Current	per channel, \overline{DIS} tied to GND		13		μA
Input Characteristics						
R_{IN}	Input Resistance	Non-inverting		>10		M Ω
C_{IN}	Input Capacitance			1.4		pF
CMIR	Common Mode Input Range			-0.3 to 1.5		V
CMRR	Common Mode Rejection Ratio	DC, $V_{CM} = 0\text{V}$ to $V_S - 1.5$		92		dB
Output Characteristics						
V_{OUT}	Output Voltage Swing	$R_L = 2\text{k}\Omega$ to $V_S / 2$		0.08 to 2.6		V
		$R_L = 10\text{k}\Omega$ to $V_S / 2$		0.06 to 2.62		V
I_{OUT}	Output Current			± 8		mA
I_{SC}	Short Circuit Output Current			± 12.5		mA

Notes:

- 100% tested at 25°C



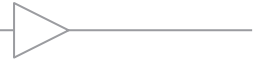
Electrical Characteristics at +5V

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 2.5\text{k}\Omega$, $R_L = 2\text{k}\Omega$ to $V_S/2$, $G = 2$; unless otherwise noted.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Frequency Domain Response						
$UGBW_{SS}$	Unity Gain -3dB Bandwidth	$G = +1$, $V_{OUT} = 0.05V_{pp}$, $R_f = 0$		35		MHz
BW_{SS}	-3dB Bandwidth	$G = +2$, $V_{OUT} < 0.2V_{pp}$		18		MHz
BW_{LS}	Large Signal Bandwidth	$G = +2$, $V_{OUT} = 2V_{pp}$		8		MHz
GBWP	Gain Bandwidth Product	$G = +11$, $V_{OUT} = 0.2V_{pp}$		20		MHz
Time Domain Response						
t_R, t_F	Rise and Fall Time	$V_{OUT} = 0.2\text{V}$ step; (10% to 90%)		13		ns
t_S	Settling Time to 0.1%	$V_{OUT} = 1\text{V}$ step		140		ns
OS	Overshoot	$V_{OUT} = 1\text{V}$ step		1		%
SR	Slew Rate	2V step, $G = -1$		27		V/ μs
Distortion/Noise Response						
HD2	2nd Harmonic Distortion	$V_{OUT} = 2V_{pp}$, 100kHz		-78		dBc
HD3	3rd Harmonic Distortion	$V_{OUT} = 2V_{pp}$, 100kHz		-66		dBc
THD	Total Harmonic Distortion	$V_{OUT} = 2V_{pp}$, 100kHz		65		dB
e_n	Input Voltage Noise	> 10kHz		21		nV/ $\sqrt{\text{Hz}}$
X_{TALK}	Crosstalk	$V_{OUT} = 0.2V_{pp}$, 100kHz		98		dB
DC Performance						
V_{IO}	Input Offset Voltage ⁽¹⁾		-5	-1.5	5	mV
dV_{IO}	Average Drift			20		$\mu\text{V}/^\circ\text{C}$
I_b	Input Bias Current ⁽¹⁾		-1.3	0.37	1.3	μA
dI_b	Average Drift			1		nA/ $^\circ\text{C}$
I_{OS}	Input Offset Current ⁽¹⁾			7	130	nA
PSRR	Power Supply Rejection Ratio ⁽¹⁾	DC	56	60		dB
A_{OL}	Open-Loop Gain	$V_{OUT} = V_S / 2$	56	62		dB
I_S	Supply Current ⁽¹⁾	per channel		208	260	μA
Disable Characteristics						
T_{ON}	Turn On Time			0.7		μs
T_{OFF}	Turn Off Time			4.5		μs
OFF_{ISO}	Off Isolation	1MHz		72		dB
I_{SD}	Disable Supply Current ⁽¹⁾	per channel, \overline{DIS} tied to GND		35		μA
Input Characteristics						
R_{IN}	Input Resistance	Non-inverting		>10		M Ω
C_{IN}	Input Capacitance			1.2		pF
CMIR	Common Mode Input Range			-0.3 to 3.8		V
CMRR	Common Mode Rejection Ratio ⁽¹⁾	DC, $V_{CM} = 0\text{V}$ to $V_S - 1.5$	65	95		dB
Output Characteristics						
V_{OUT}	Output Voltage Swing	$R_L = 2\text{k}\Omega$ to $V_S / 2$ ⁽¹⁾	0.2 to 4.7	0.1 to 4.8		V
		$R_L = 10\text{k}\Omega$ to $V_S / 2$		0.08 to 4.88		V
I_{OUT}	Output Current			± 8.5		mA
I_{SC}	Short Circuit Output Current			± 13		mA

Notes:

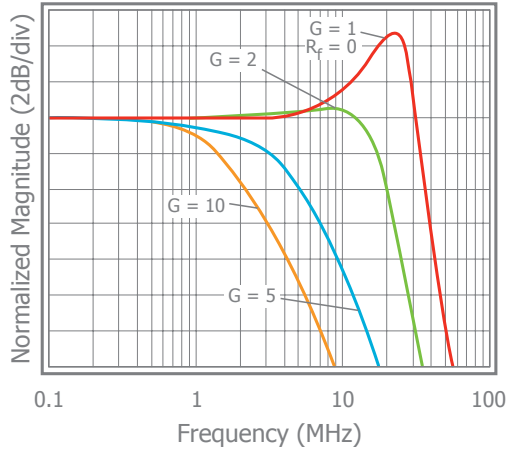
1. 100% tested at 25°C



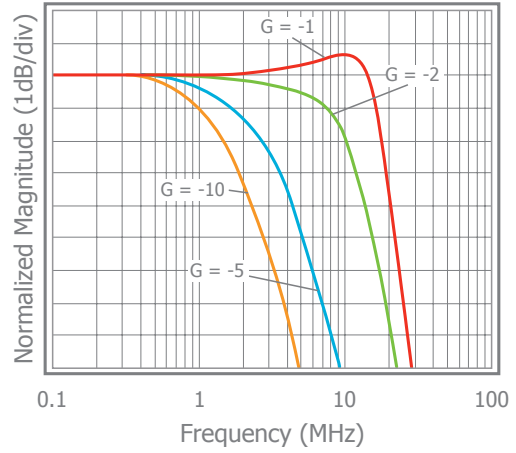
Typical Performance Characteristics

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 2.5\text{k}\Omega$, $R_L = 2\text{k}\Omega$ to $V_S/2$, $G = 2$; unless otherwise noted.

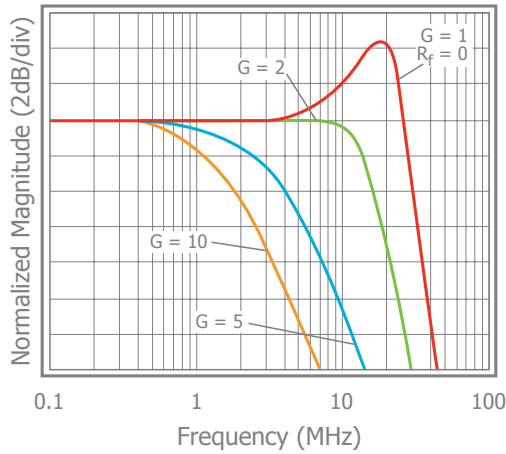
Non-Inverting Frequency Response



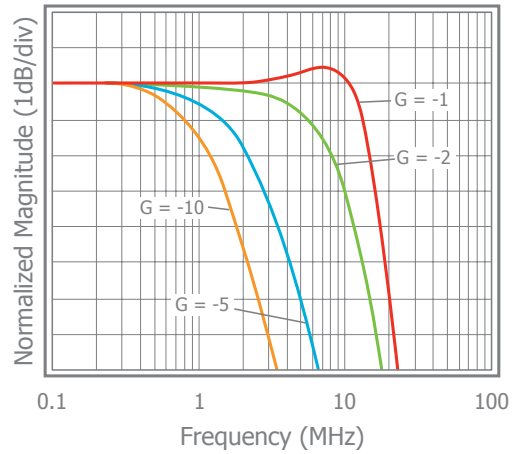
Inverting Frequency Response



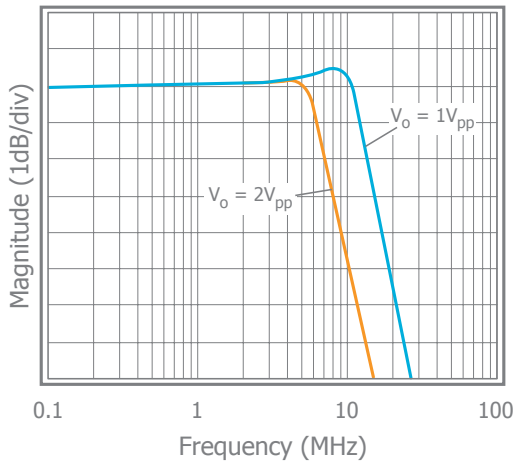
Non-Inverting Frequency Response at $V_S = 2.7\text{V}$



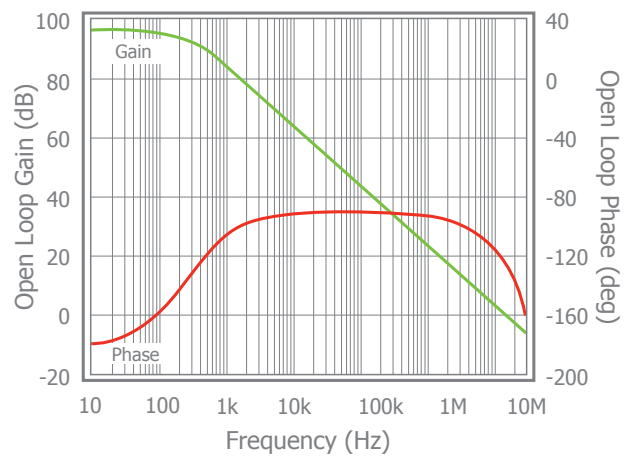
Inverting Frequency Response at $V_S = 2.7\text{V}$

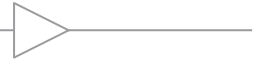


Frequency Response vs. V_{OUT}



Open Loop Gain & Phase vs. Frequency

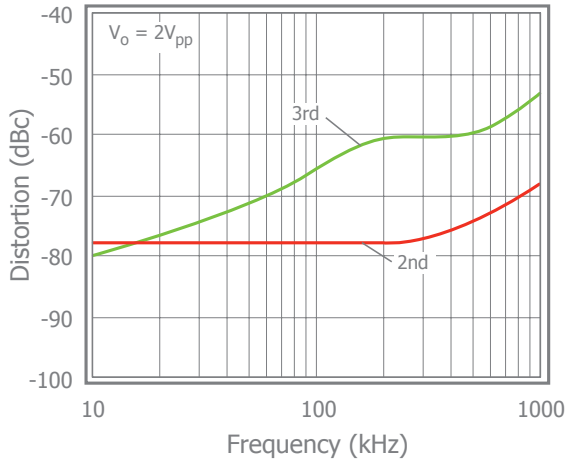




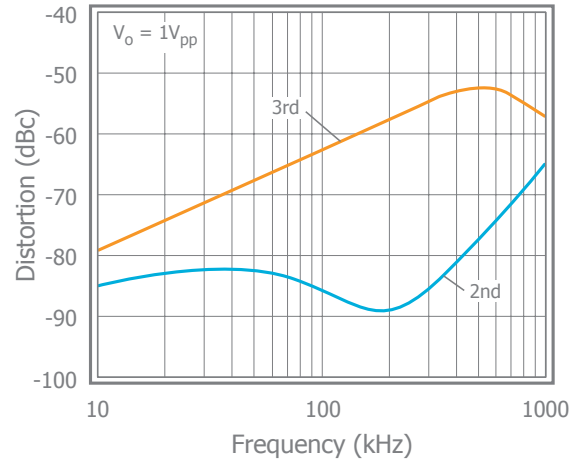
Typical Performance Characteristics

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 2.5\text{k}\Omega$, $R_L = 2\text{k}\Omega$ to $V_S/2$, $G = 2$; unless otherwise noted.

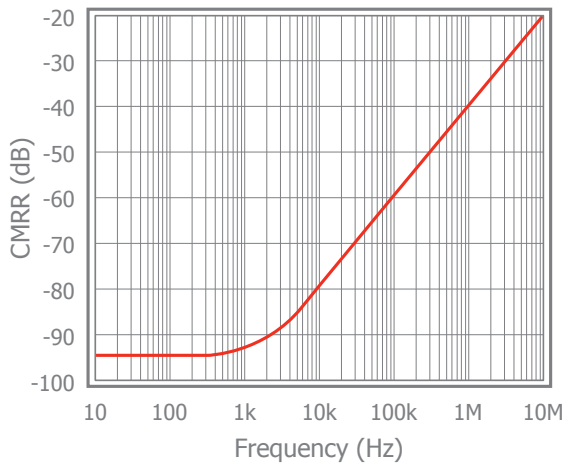
2nd & 3rd Harmonic Distortion



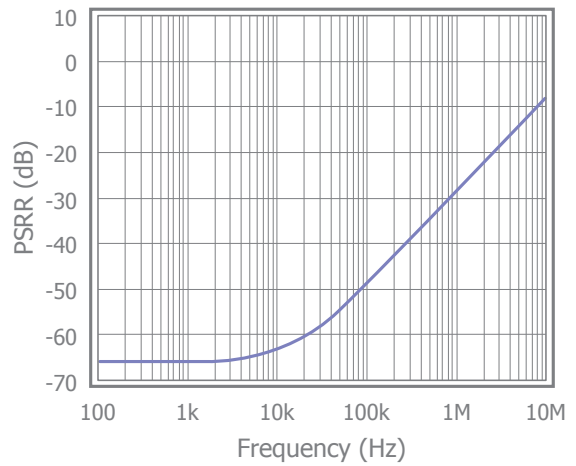
2nd & 3rd Harmonic Distortion at $V_S = 2.7\text{V}$



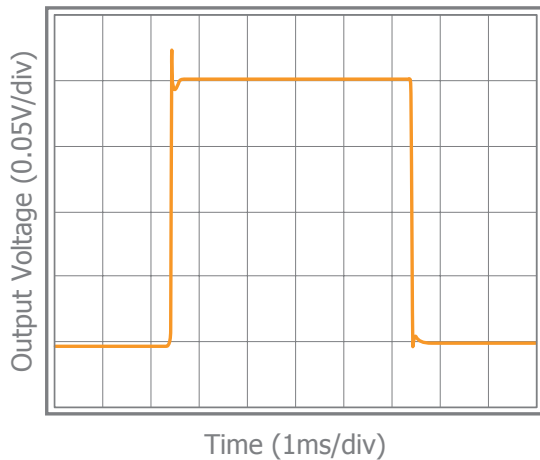
CMRR



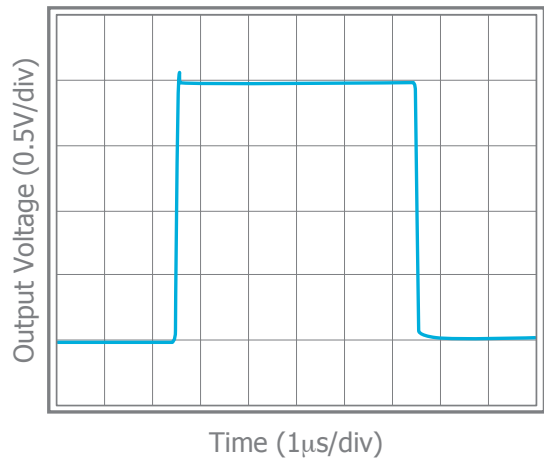
PSRR



Small Signal Pulse Response



Large Signal Pulse Response

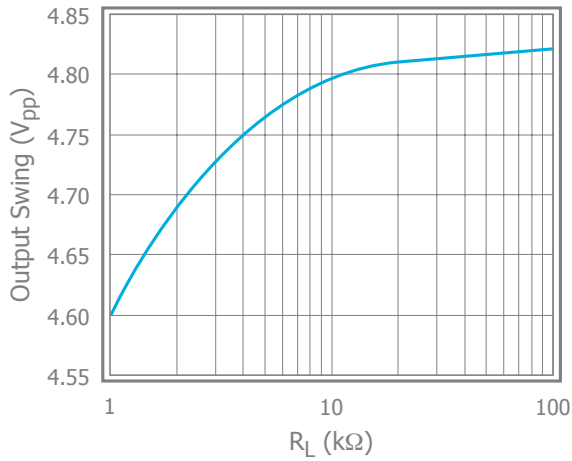




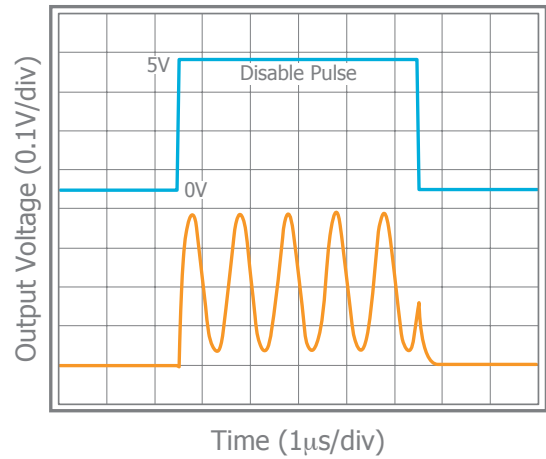
Typical Performance Characteristics - Continued

$T_A = 25^\circ\text{C}$, $V_S = +5\text{V}$, $R_f = R_g = 2.5\text{k}\Omega$, $R_L = 2\text{k}\Omega$ to $V_S/2$, $G = 2$; unless otherwise noted.

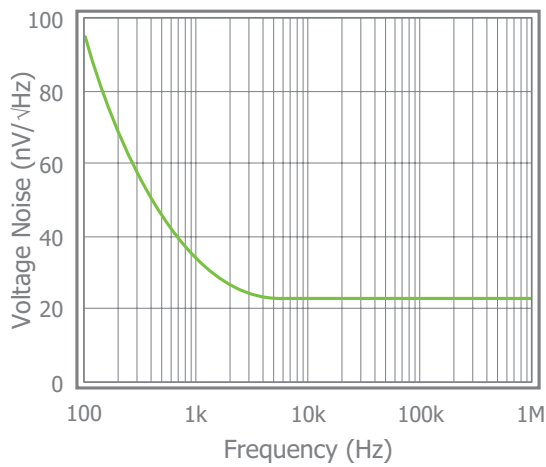
Output Swing vs. R_L



Enable / Disable Response



Input Voltage Noise





Application Information

General Description

The CLC1009 family are a single supply, general purpose, voltage-feedback amplifiers fabricated on a complementary bipolar process. The CLC1009 offers 35MHz unity gain bandwidth, 27V/ μ s slew rate, and only 208 μ A supply current. It features a rail-to-rail output stage and is unity gain stable.

The design utilizes a patent pending topology that provides increased slew rate performance. The common mode input range extends to 300mV below ground and to 1.2V below V_s . Exceeding these values will not cause phase reversal. However, if the input voltage exceeds the rails by more than 0.5V, the input ESD devices will begin to conduct. The output will stay at the rail during this overdrive condition.

The design uses a Darlington output stage. The output stage is short circuit protected and offers "soft" saturation protection that improves recovery time.

Figures 1, 2, and 3 illustrate typical circuit configurations for non-inverting, inverting, and unity gain topologies for dual supply applications. They show the recommended bypass capacitor values and overall closed loop gain equations. Figure 4 shows the typical non-inverting gain circuit for single supply applications.

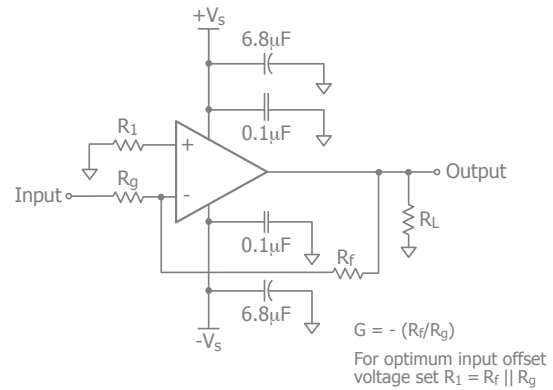


Figure 2. Typical Inverting Gain Circuit

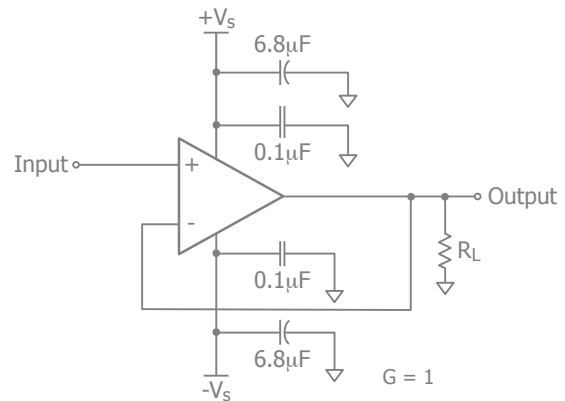


Figure 3. Unity Gain Circuit

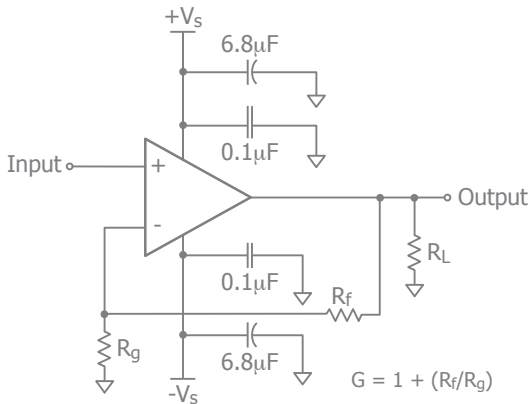


Figure 1. Typical Non-Inverting Gain Circuit

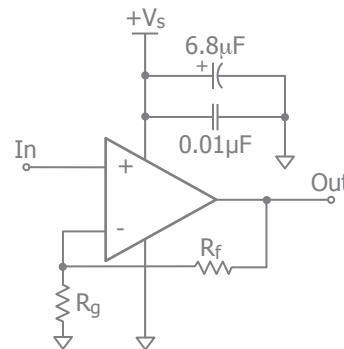


Figure 4. Single Supply Non-Inverting Gain Circuit



Enable/Disable Function (CLC1019)

The CLC1019 offers an active-low disable pin that can be used to lower its supply current. Leave the pin floating to enable the part. Pull the disable pin to the negative supply (which is ground in a single supply application) to disable the output. During the disable condition, the nominal supply current will drop to below 40µA and the output will be at high impedance with about 2pF capacitance.

Power Dissipation

Power dissipation should not be a factor when operating under the stated 2kΩ load condition. However, applications with low impedance, DC coupled loads should be analyzed to ensure that maximum allowed junction temperature is not exceeded. Guidelines listed below can be used to verify that the particular application will not cause the device to operate beyond its intended operating range.

Maximum power levels are set by the absolute maximum junction rating of 150°C. To calculate the junction temperature, the package thermal resistance value Θ_{JA} (Θ_{JA}) is used along with the total die power dissipation.

$$T_{\text{Junction}} = T_{\text{Ambient}} + (\Theta_{JA} \times P_D)$$

Where T_{Ambient} is the temperature of the working environment.

In order to determine P_D , the power dissipated in the load needs to be subtracted from the total power delivered by the supplies.

$$P_D = P_{\text{supply}} - P_{\text{load}}$$

Supply power is calculated by the standard power equation.

$$P_{\text{supply}} = V_{\text{supply}} \times I_{\text{RMS supply}}$$

$$V_{\text{supply}} = V_{S+} - V_{S-}$$

Power delivered to a purely resistive load is:

$$P_{\text{load}} = ((V_{\text{LOAD}})_{\text{RMS}}^2) / R_{\text{load eff}}$$

The effective load resistor ($R_{\text{load eff}}$) will need to include the effect of the feedback network. For instance,

$R_{\text{load eff}}$ in Figure 3 would be calculated as:

$$R_L \parallel (R_f + R_g)$$

These measurements are basic and are relatively easy to perform with standard lab equipment. For design purposes however, prior knowledge of actual signal levels and load

impedance is needed to determine the dissipated power. Here, P_D can be found from

$$P_D = P_{\text{Quiescent}} + P_{\text{Dynamic}} - P_{\text{Load}}$$

Quiescent power can be derived from the specified I_S values along with known supply voltage, V_{Supply} . Load power can be calculated as above with the desired signal amplitudes using:

$$(V_{\text{LOAD}})_{\text{RMS}} = V_{\text{PEAK}} / \sqrt{2}$$

$$(I_{\text{LOAD}})_{\text{RMS}} = (V_{\text{LOAD}})_{\text{RMS}} / R_{\text{load eff}}$$

The dynamic power is focused primarily within the output stage driving the load. This value can be calculated as:

$$P_{\text{DYNAMIC}} = (V_{S+} - V_{\text{LOAD}})_{\text{RMS}} \times (I_{\text{LOAD}})_{\text{RMS}}$$

Assuming the load is referenced in the middle of the power rails or $V_{\text{supply}}/2$.

The CLC1009 is short circuit protected. However, this may not guarantee that the maximum junction temperature (+150°C) is not exceeded under all conditions. Figure 5 shows the maximum safe power dissipation in the package vs. the ambient temperature for the packages available.

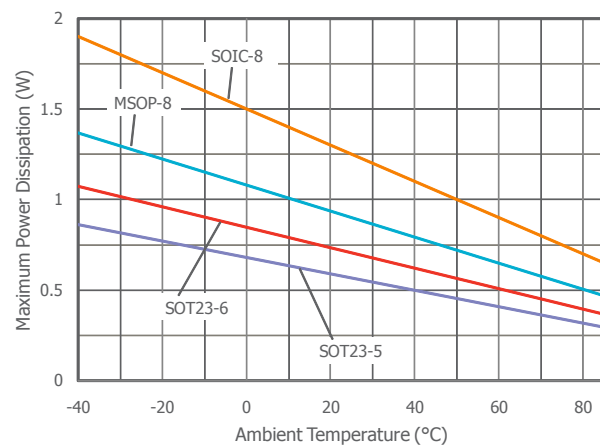


Figure 5. Maximum Power Derating

Driving Capacitive Loads

Increased phase delay at the output due to capacitive loading can cause ringing, peaking in the frequency response, and possible unstable behavior. Use a series resistance, R_S , between the amplifier and the load to help improve stability and settling performance. Refer to Figure 6.

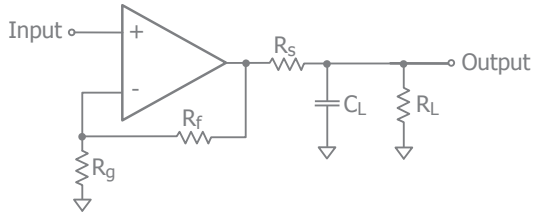
Figure 6. Addition of R_S for Driving Capacitive Loads

Table 1 provides the recommended R_S for various capacitive loads. The recommended R_S values result in approximately <1dB peaking in the frequency response.

C_L (pF)	R_S (Ω)	-3dB BW (kHz)
10pF	TBD	
20pF	TBD	
50pF	TBD	
100pF	TBD	

Table 1: Recommended R_S vs. C_L

For a given load capacitance, adjust R_S to optimize the tradeoff between settling time and bandwidth. In general, reducing R_S will increase bandwidth at the expense of additional overshoot and ringing.

Overdrive Recovery

An overdrive condition is defined as the point when either one of the inputs or the output exceed their specified voltage range. Overdrive recovery is the time needed for the amplifier to return to its normal or linear operating point. The recovery time varies, based on whether the input or output is overdriven and by how much the range is exceeded. The CLC1009, CLC1019, and CLC2009 will typically recover in less than 20ns from an overdrive condition. Figure 7 shows the CLC1009 in an overdriven condition.

Figure 7. Overdrive Recovery

Layout Considerations

General layout and supply bypassing play major roles in high frequency performance. CADEKA has evaluation boards to use as a guide for high frequency layout and as an aid in device testing and characterization. Follow the steps below as a basis for high frequency layout:

- Include 6.8 μ F and 0.1 μ F ceramic capacitors for power supply decoupling
- Place the 6.8 μ F capacitor within 0.75 inches of the power pin
- Place the 0.1 μ F capacitor within 0.1 inches of the power pin
- Remove the ground plane under and around the part, especially near the input and output pins to reduce parasitic capacitance
- Minimize all trace lengths to reduce series inductances

Refer to the evaluation board layouts below for more information.

Evaluation Board Information

The following evaluation boards are available to aid in the testing and layout of these devices:

Evaluation Board	Products
CEB002	CLC1009, CLC1019 in SOT23
CEB003	CLC1009 in SOIC
CEB006	CLC2009 in SOIC
CEB010	CLC2009 in MSOP



Evaluation Board Schematics

Evaluation board schematics and layouts are shown in Figures 8-14. These evaluation boards are built for dual-supply operation. Follow these steps to use the board in a single-supply application:

1. Short -Vs to ground.
2. Use C3 and C4, if the -Vs pin of the amplifier is not directly connected to the ground plane.

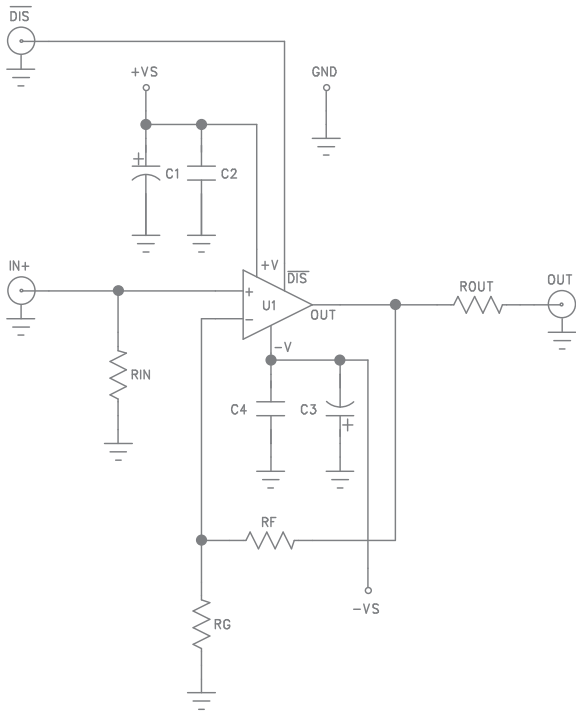


Figure 8. CEB002 & CEB003 Schematic

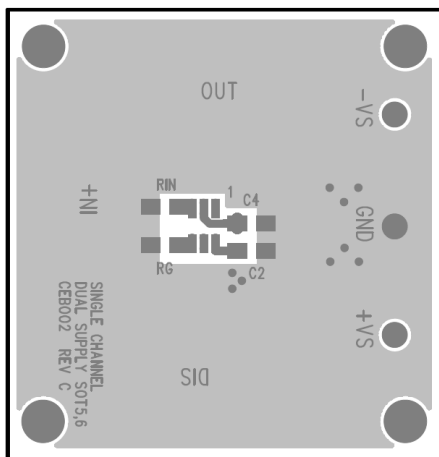


Figure 9. CEB002 Top View

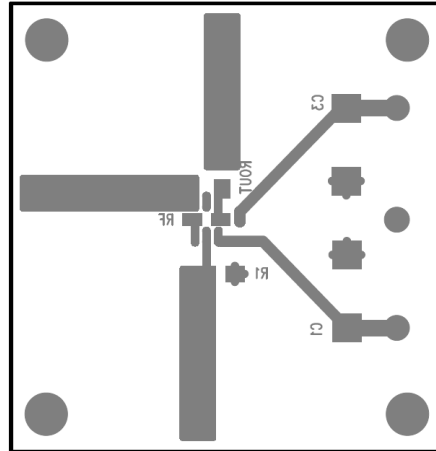


Figure 10. CEB002 Bottom View

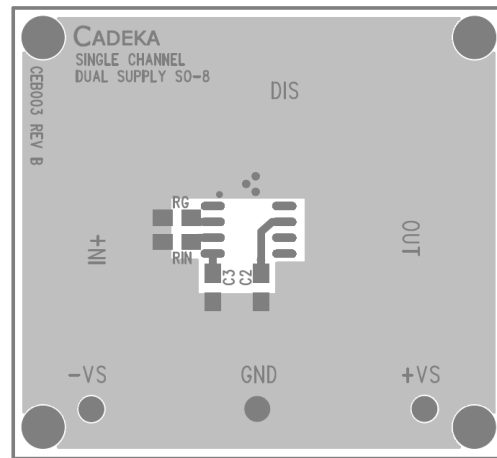


Figure 11. CEB003 Top View

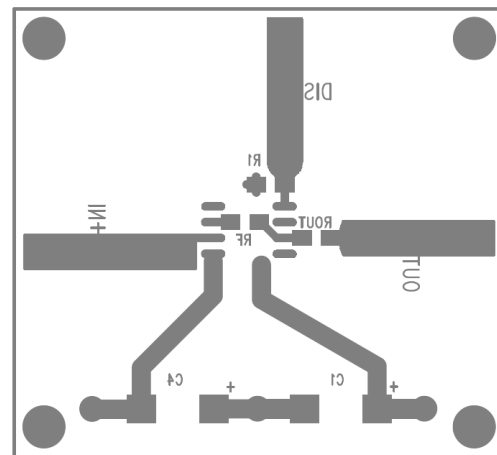


Figure 12. CEB003 Bottom View

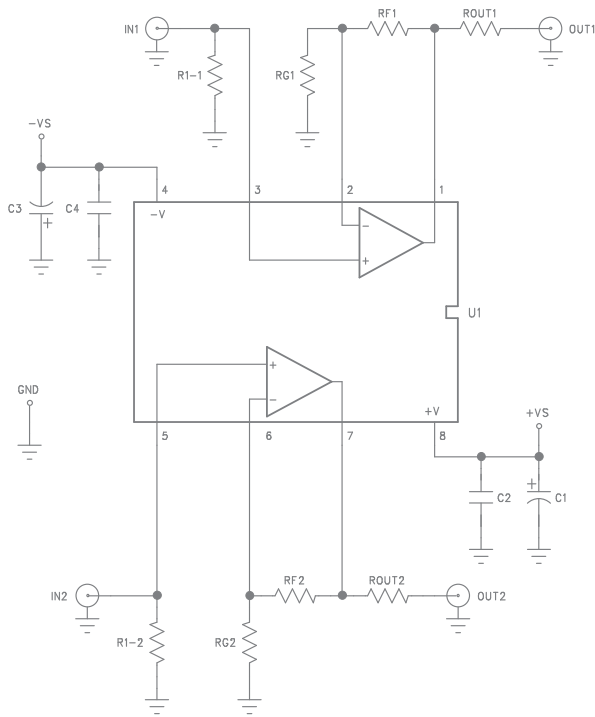


Figure 11. CEB006 & CEB010 Schematic

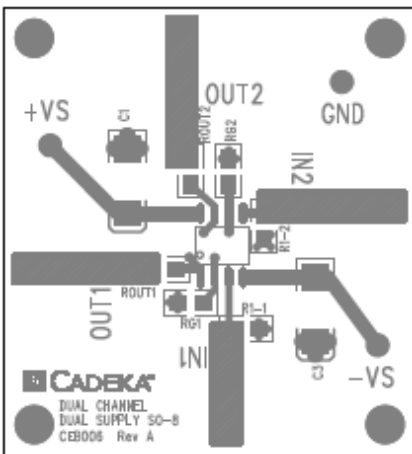


Figure 12. CEB006 Top View

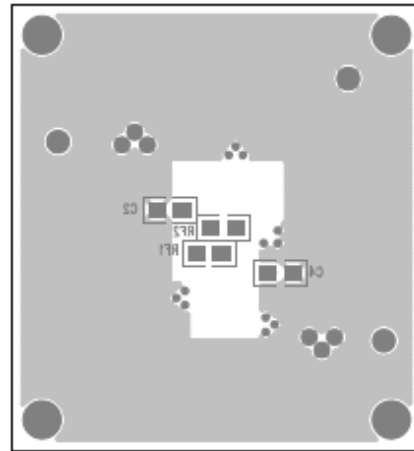


Figure 13. CEB006 Bottom View

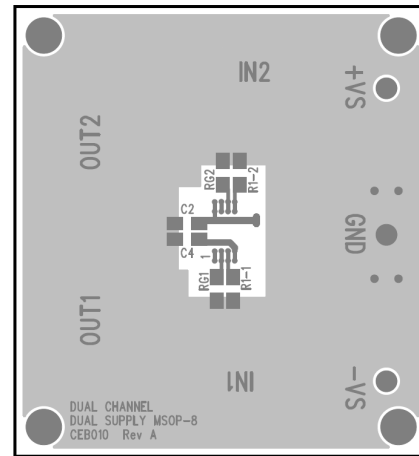


Figure 15. CEB010 Top View

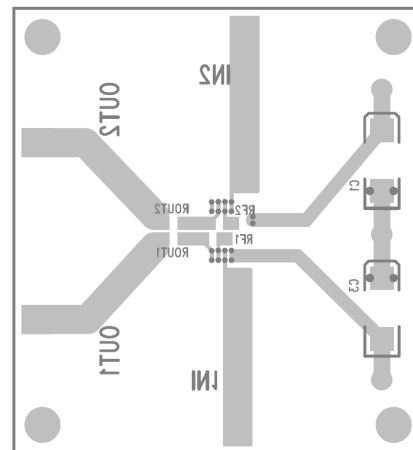
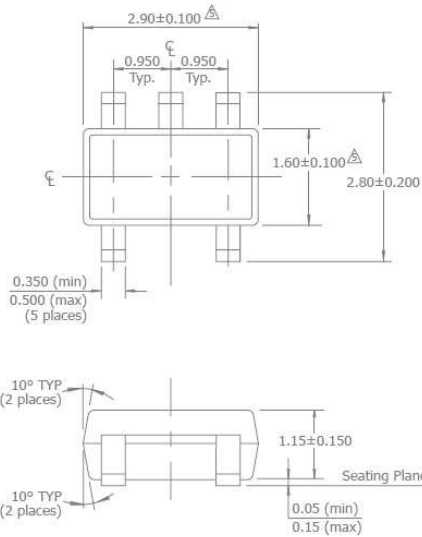


Figure 16. CEB010 Bottom View



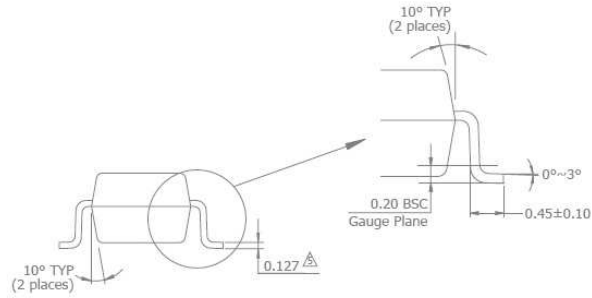
Mechanical Dimensions

SOT23-5 Package

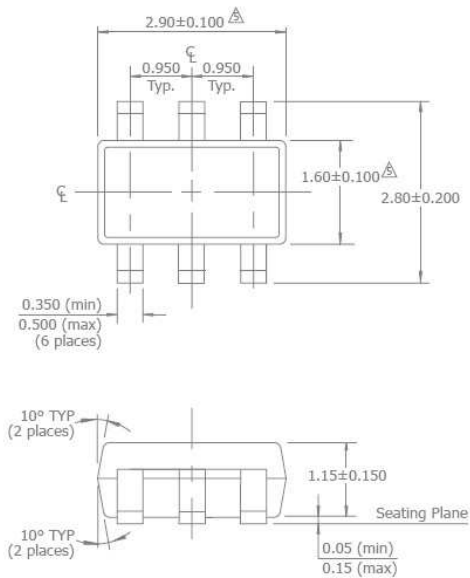


NOTES:

1. Dimensions and tolerances are as per ANSI Y14.5M-1982.
 2. Package surface to be matte finish VDI 11~13.
 3. Die is facing up for mold. Die is facing down for trim/form, ie. reverse trim/form.
 4. The footlength measuring is based on the guage plane method.
- △ Dimension are exclusive of mold flash and gate burr.
 △ Dimension are exclusive of solder plating.

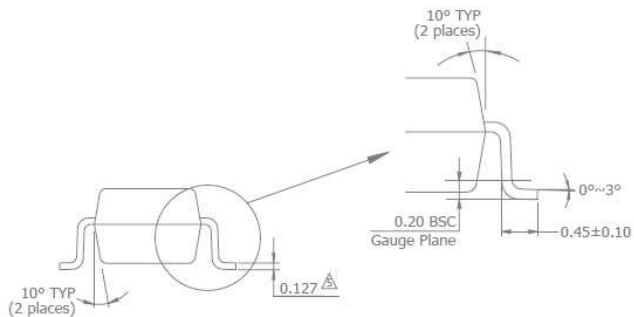


SOT23-6



NOTES:

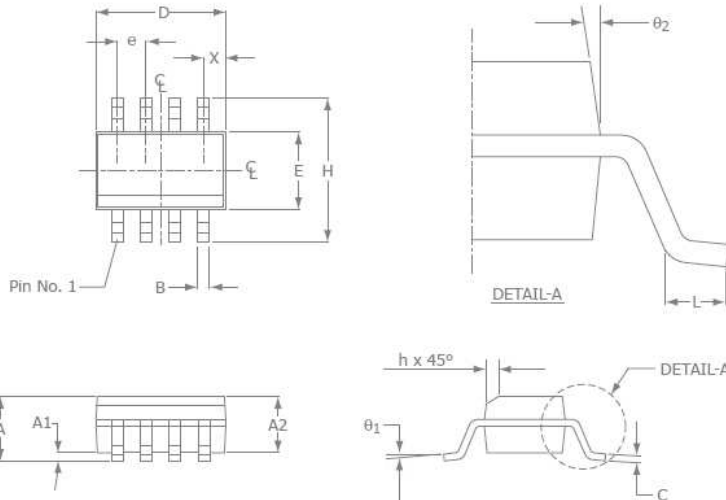
1. Dimensions and tolerances are as per ANSI Y14.5M-1982.
 2. Package surface to be matte finish VDI 11~13.
 3. Die is facing up for mold. Die is facing down for trim/form, ie. reverse trim/form.
 4. The footlength measuring is based on the guage plane method.
- △ Dimension are exclusive of mold flash and gate burr.
 △ Dimension are exclusive of solder plating.





Mechanical Dimensions continued

SOIC-8 Package

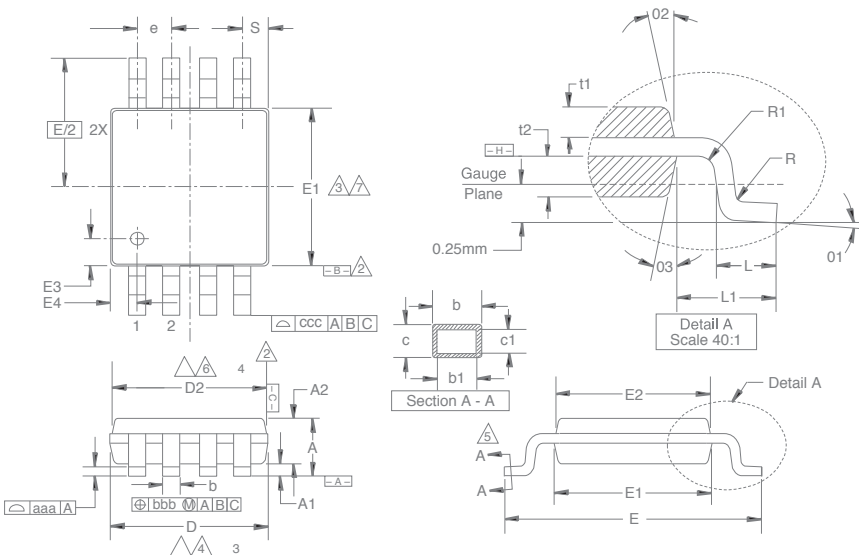


SOIC-8		
SYMBOL	MIN	MAX
A1	0.10	0.25
B	0.36	0.48
C	0.19	0.25
D	4.80	4.98
E	3.81	3.99
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.5
L	0.41	1.27
A	1.37	1.73
theta1	0°	8°
X	0.55 ref	
theta2	7° BSC	

NOTE:

1. All dimensions are in millimeters.
2. Lead coplanarity should be 0 to 0.1mm (0.004") max.
3. Package surface finishing: VDI 24~27
4. All dimension excluding mold flashes.
5. The lead width, B to be determined at 0.1905mm from the lead tip.

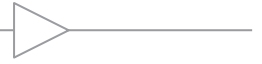
MSOP-8 Package



Symbol	Min	Max
A	1.10	-
A1	0.10	±0.05
A2	0.86	±0.08
D	3.00	±0.10
D2	2.95	±0.10
E	4.90	±0.15
E1	3.00	±0.10
E2	2.95	±0.10
E3	0.51	±0.13
E4	0.51	±0.13
R	0.15	+0.15/-0.06
R1	0.15	+0.15/-0.06
t1	0.31	±0.08
t2	0.41	±0.08
b	0.33	+0.07/-0.08
b1	0.30	±0.05
c	0.18	±0.05
c1	0.15	+0.03/-0.02
theta1	3.0°	±3.0°
theta2	12.0°	±3.0°
theta3	12.0°	±3.0°
L	0.55	±0.15
L1	0.95 BSC	-
aaa	0.10	-
bbb	0.08	-
ccc	0.25	-
e	0.65 BSC	-
S	0.525 BSC	-

NOTE:

1. All dimensions are in millimeters (angle in degrees), unless otherwise specified.
- ▲ Datum symbols $\square-B$ and $\square-C$ to be determined at datum plane $\square-H$.
- ▲ Dimensions "D" and "E1" are to be determined at datum $\square-H$.
- ▲ Dimensions "D2" and "E2" are for top package and dimensions "D" and "E1" are for bottom package.
- ▲ Cross sections A - A to be determined at 0.13 to 0.25mm from the leadtip.
- ▲ Dimension "D" and "D2" does not include mold flash, protrusion or gate burrs.
- ▲ Dimension "E1" and "E2" does not include interlead flash or protrusion.



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